

# HVB190S

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0440-0100 (Previous: ADE-208-1597) Rev.1.00 Dec 20, 2004

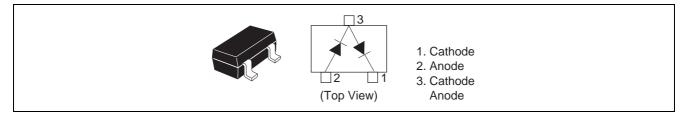
### Features

- Low capacitance. (C = 0.35 pF max)
- Low forward resistance. ( $rf = 3.0 \Omega typ$ )
- CMPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Code	
HVB190S	Н9	CMPAK	

### **Pin Arrangement**





# Absolute Maximum Ratings \*1

 $(Ta = 25^{\circ}C)$ 

ltem	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	50	V
Forward current	lF	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Note: 1. Absolute maximum ratings are described each unit separately.

## Electrical Characteristics\*1

(Ta = 25°C)

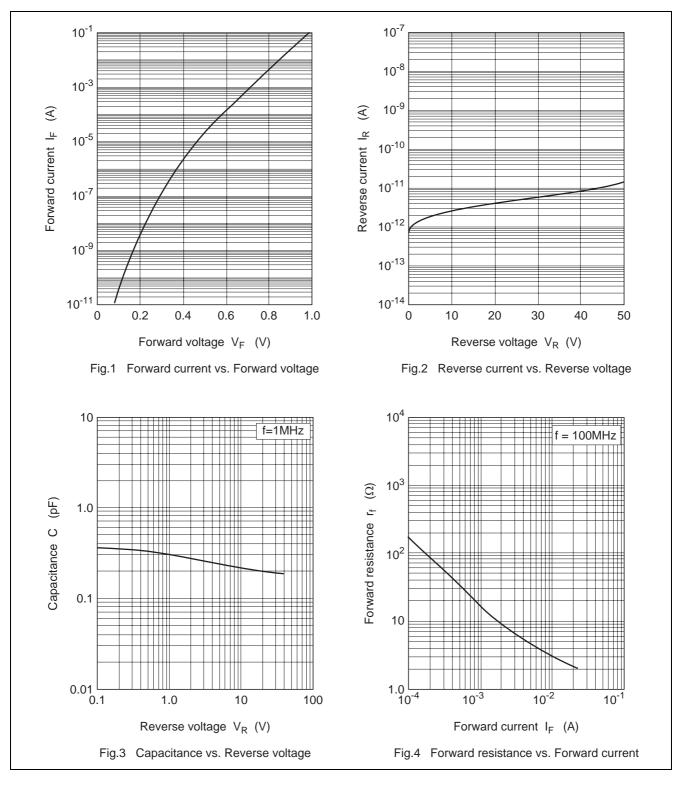
Symbol	Min	Тур	Max	Unit	Test Condition
VF		-	1.0	V	I <sub>F</sub> = 50 mA
I <sub>R</sub>		-	100	nA	V <sub>R</sub> = 50 V
С		_	0.35	pF	V <sub>R</sub> = 50 V, f = 1 MHz
r <sub>f</sub>		3.0	5.0	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
—	200			V	C = 200 pF, Both forward and reverse direction 1 pulse
	V <sub>F</sub> I <sub>R</sub> C	V <sub>F</sub> — I <sub>R</sub> — C — r <sub>f</sub> —	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

Notes: 1. Per one device.

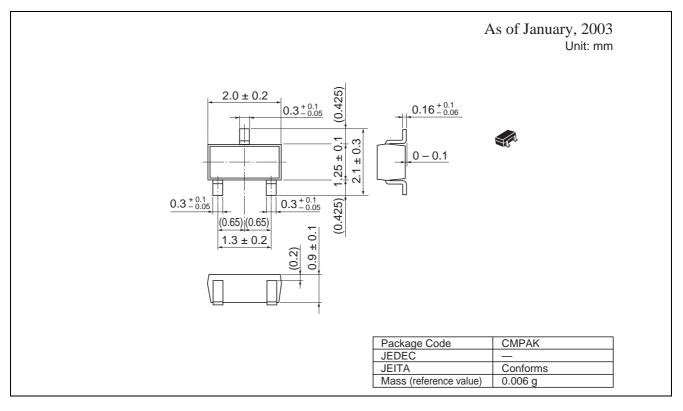
2. Failure criterion;  $I_R \geq 200~nA$  at  $V_R$  = 50 V



### **Main Characteristic**



### Package Dimensions





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